

Features

- Integrally molded heat sink provides low thermal resistance for maximum heat dissipation
- Types up to 1000 V V_{RRM}
 - Void-free junction by using vacuum soldering
- High surge current capability
- High temperature soldering guaranteed: 260°C/ 10 seconds at 5 lbs(2.3 kg) tension
- Universal 3-way terminals: snap on, wire-around, or P.C board mounting

GBPC-T/W Package



Mechanical Data

Case: Molded plastic with heat sink mounted in the bridge
 Mounting position: Bolt down on heat-sink with silicone thermal compound between bridge and mounting surface
 Terminals: Either nickel plated 0.25"(6.35 mm) Faston lugs or 0.040"(1.02 mm) diameter copper leads.
 Weight: 19 grams or 0.67 ounces
 Mounting torque: 20 inch-lbs max
 Polarity: Marked on body

Maximum ratings, at $T_j = 25\text{ }^\circ\text{C}$, unless otherwise specified (GBPCXXXXT uses GBPC-T package while GBPCXXXXW uses GBPC-W package)

Parameter	Symbol	Conditions	GBPC50005T/W	GBPC5001T/W	GBPC5002T/W	GBPC5004T/W	Unit
Repetitive peak reverse voltage	V_{RRM}		50	100	200	400	V
RMS reverse voltage	V_{RMS}		35	70	140	280	V
DC blocking voltage	V_{DC}		50	100	200	400	V
Continuous forward current	I_F	$T_C \leq 50\text{ }^\circ\text{C}$	50	50	50	50	A
Surge non-repetitive forward current, Half Sine Wave	$I_{F,SM}$	$T_C = 25\text{ }^\circ\text{C}, t_p = 8.3\text{ ms}$	400	400	400	400	A
Operating temperature	T_j		-55 to 150	-55 to 150	-55 to 150	-55 to 150	$^\circ\text{C}$
Storage temperature	T_{stg}		-55 to 150	-55 to 150	-55 to 150	-55 to 150	$^\circ\text{C}$

Electrical characteristics, at $T_j = 25\text{ }^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	GBPC50005T/W	GBPC5001T/W	GBPC5002T/W	GBPC5004T/W	Unit
Diode forward voltage	V_F	$I_F = 25\text{ A}, T_j = 25\text{ }^\circ\text{C}$	1.2	1.2	1.2	1.2	V
Reverse current	I_R	$V_R = 50\text{ V}, T_j = 25\text{ }^\circ\text{C}$ $V_R = 50\text{ V}, T_j = 125\text{ }^\circ\text{C}$	5 500	5 500	5 500	5 500	μA
Thermal characteristics							
Thermal resistance, junction - case	R_{thJC}		1.2	1.2	1.2	1.2	$^\circ\text{C/W}$



America Semiconductor

GBPC50005TW thru GBPC5004TW

FIG.5-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS PER LEG

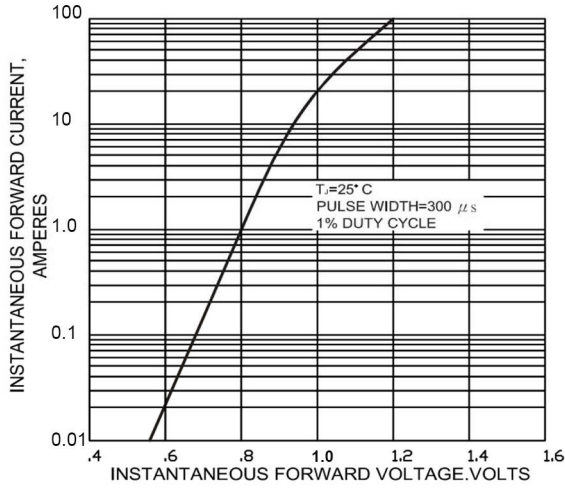


FIG.6-TYPICAL REVERSE CHARACTERISTICS

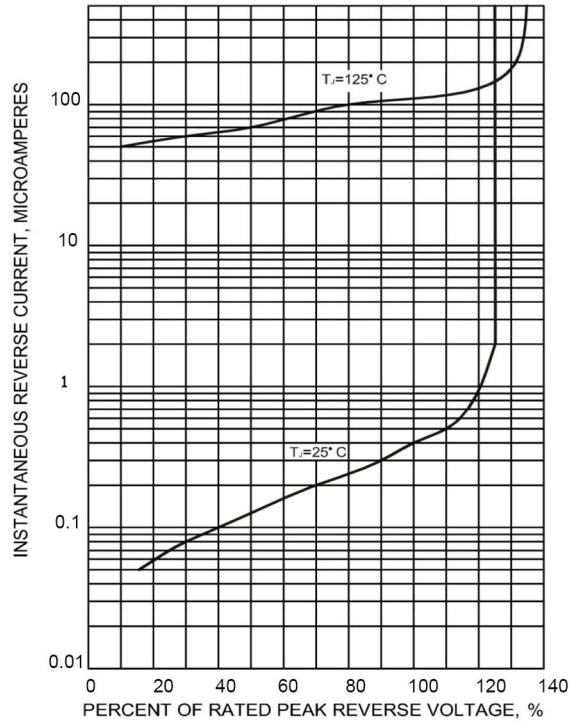


FIG.7-TYPICAL JUNCTION CAPACITANCE PER LEG

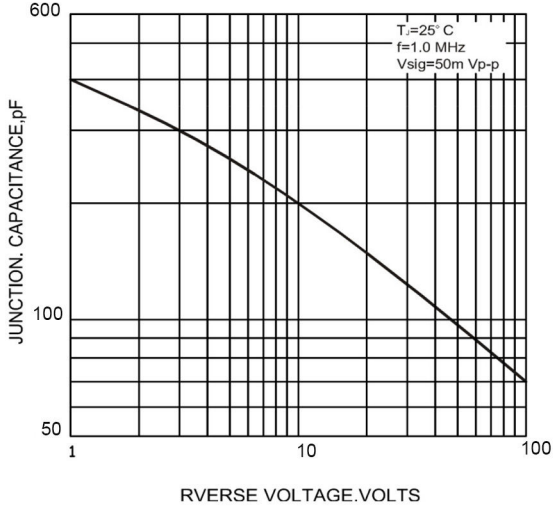


FIG.8-TYPICAL TRANSIENT THERMAL IMPEDANCE

